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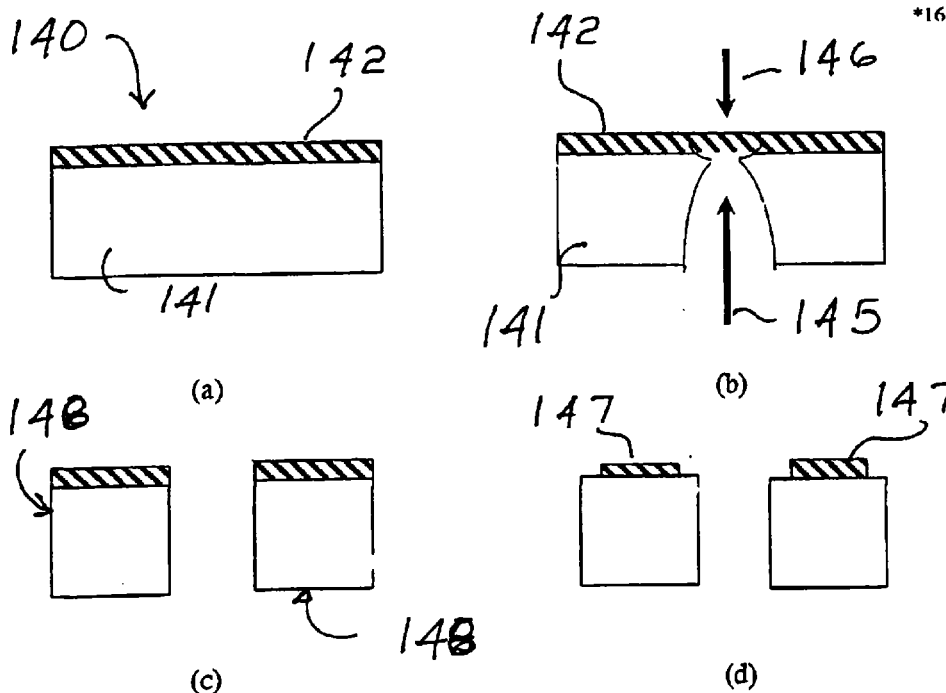
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(54) Title: LASER MACHINING OF SEMICONDUCTOR MATERIALS



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(57) Abstract: A semiconductor is cut by directing a green laser beam of high power, and subsequently a UV beam along the cut line. The first beam performs cutting with relatively rough edges and a high material removal rate, and the second beam completes the cut at the edges for the required finish, with a lower material quantity removal.

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